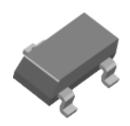
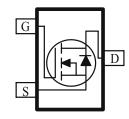
N-Channel 20V (D-S) MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low $r_{DS(on)}$ and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

| PRODUCT SUMMARY | | | |
|-----------------|----------------------------------|-----|--|
| $V_{DS}(V)$ | $V_{DS}(V)$ $r_{DS(on)}(\Omega)$ | | |
| 20 | $0.058 @V_{CS} = 4.5 V$ | 2.0 | |
| | $0.082 @V_{CS} = 2.5V$ | 1.7 | |

- Low r_{DS(on)} provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe SC70-3 saves board space
- Fast switching speed
- High performance trench technology





| ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C UNLESS OTHERWISE NOTED) | | | | | |
|--|--|------------------|------------|-------|--|
| Parameter | | Symbol | Maximum | Units | |
| Drain-Source Voltage | | V_{DS} | 20 | V | |
| Gate-Source Voltage | | | ±8 | V | |
| Continuous Drain Current ^a | $T_A=25^{\circ}C$ | T | 2.0 | | |
| Continuous Drain Current | $T_A=25^{\circ}C$ $T_A=70^{\circ}C$ | ц | 1.7 | A | |
| Pulsed Drain Current ^b | | I_{DM} | ±20 | | |
| Continuous Source Current (Diode Conduction) ^a | | I_S | 1.6 | A | |
| D D: : ,: a | $T_A=25^{\circ}C$ | D | 0.34 | w | |
| Power Dissipation ^a | $T_A=25^{\circ}C$ $T_A=70^{\circ}C$ | LD | 0.22 | VV | |
| Operating Junction and Storage Temperature Range | | T_{J}, T_{stg} | -55 to 150 | °C | |

| THERMAL RESISTANCE RATINGS | | | | | | |
|--|--------------|-------------------|---------------|------|--|--|
| Parameter | | Symbol | Maximum Units | | | |
| Maximum Junction-to-Ambient ^a | t <= 5 sec | D | 100 | °C/W | | |
| | Steady-State | R _{THJA} | 166 | | | |

Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

| SPECIFICATIONS (T _A = 25°C UNLESS OTHERWISE NOTED) | | | | | | | |
|---|-----------------------|---|--------|------|------|---------|--|
| Parameter | Crymbal | | Limits | | | T 1-424 | |
| Parameter | Symbol | Symbol Test Conditions | | Тур | Max | Unit | |
| Static | | | | | | | |
| Gate-Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_{D} = 250 \text{ uA}$ | 0.7 | | | V | |
| Gate-Body Leakage | I_{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$ | | | ±100 | nA | |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}$ | | | 1 | uA | |
| - | -033 | $V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55^{\circ}\text{C}$ | | | 10 | | |
| On-State Drain Current ^A | I _{D(on)} | $V_{DS} = 5 \text{ V}, V_{GS} = 4.5 \text{ V}$ | 10 | | | A | |
| Drain-Source On-Resistance ^A | | $V_{GS} = 4.5 \text{ V}, I_D = 2.0 \text{ A}$ | | | 58 | mΩ | |
| Diani-Source On-Resistance | $r_{\mathrm{DS(on)}}$ | $V_{GS} = 2.5 \text{ V}, I_D = 1.7 \text{ A}$ | | | 82 | 11122 | |
| Forward Tranconductance ^A | $g_{ m fs}$ | $V_{DS} = 10 \text{ V}, I_D = 2.0 \text{ A}$ | | 11.3 | | S | |
| Diode Forward Voltage | V_{SD} | $I_S = 1.6 \text{ A}, V_{GS} = 0 \text{ V}$ | | 0.75 | | V | |
| Dynamic ^b | | | | | | | |
| Total Gate Charge | Q_{g} | | | 7.5 | | | |
| Gate-Source Charge | Q_{gs} | $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 2.0 \text{ A}$ | | 0.6 | | nC | |
| Gate-Drain Charge | Q_{gd} | | | 1.0 | | | |
| Input Capacitance | C_{iss} | V = 15 V V = 0 V | | 720 | | | |
| Output Capacitance C | | $V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz | | 165 | | pF | |
| Reverse Transfer Capacitance | C_{rss} | I – IMHZ | | 60 | | 1 | |
| Turn-On Delay Time | $t_{d(on)}$ | | | 8 | | | |
| Rise Time | $t_{\rm r}$ | $V_{DD} = 10 \text{ V}, R_L = 15 \Omega, I_D = 1 \text{ A},$ | | 24 | | | |
| Turn-Off Delay Time | $t_{d(off)}$ | $V_{GEN} = 4.5 \text{ V}$ | | 35 | | ns | |
| Fall-Time | t_{f} | | | 10 | | 1 | |

Notes

- a. Pulse test: $PW \le 300us duty cycle \le 2\%$.
- b. Guaranteed by design, not subject to production testing.

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Typical Electrical Characteristics (N-Channel)

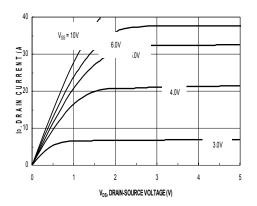


Figure 1. On-Region Characteristics

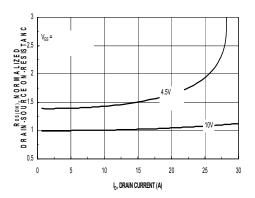


Figure 3. On Resistance Vs Vgs Voltage

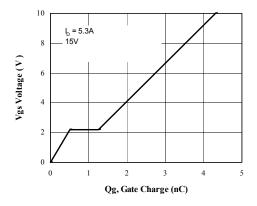


Figure 5. Gate Charge Characteristics

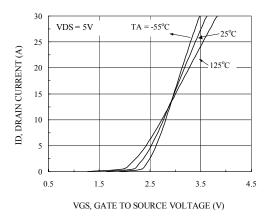


Figure 2. Body Diode Forward Voltage Variation with Source Current and Temperature

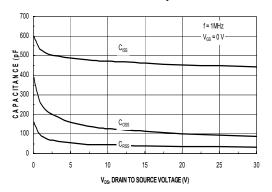


Figure 4. Capacitance Characteristics

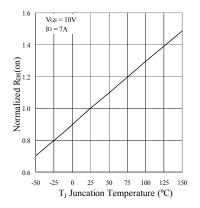


Figure 6. On-Resistance Variation with Temperature

Typical Electrical Characteristics (N-Channel)

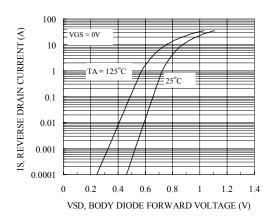


Figure 7. Transfer Characteristics

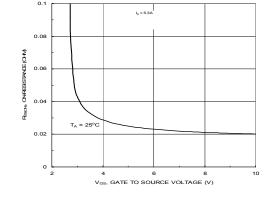


Figure 8. On-Resistance with Gate to Source Voltage

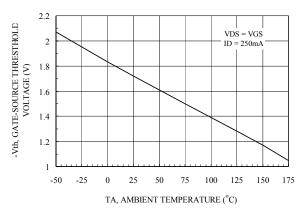


Figure 9. Vth Gate to Source Voltage Vs Temperature

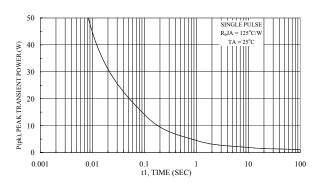


Figure 10. Single Pulse Maximum Power Dissipation

Normalized Thermal Transient Junction to Ambient

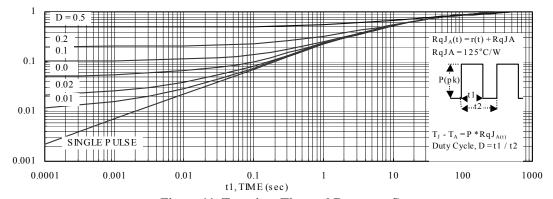


Figure 11. Transient Thermal Response Curve